June 27.2024 ICPST-41 A05-05, 10:50 - 11:10

Influence of the solvent in resist solution and thin films on aggregation size of chemical components

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Outline

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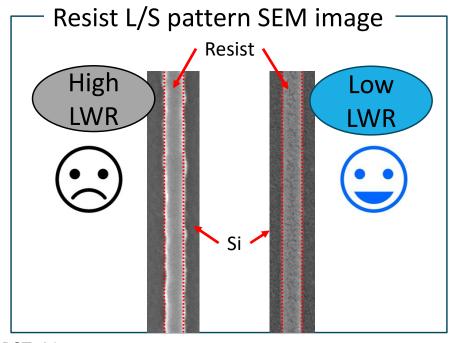
1. Introduction

- 2. Results and Discussions
 - Resist particle size analysis in solution
 <u>DLS measurement</u>
 - Aggregation size analysis in resist film (Investigation of baking temperature effect) <u>Resonant Soft X-ray Scattering</u>
- 3. Summary

Critical issue of resist materials: Line Width Roughness

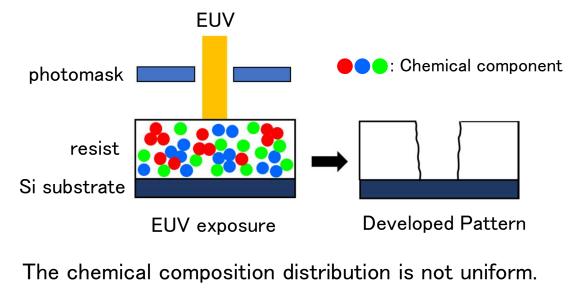
For next generation EUV lithography

- Resolution: < 10 nm</p>
- Sensitivity: < 20 mJ/cm²
- LWR (Line width roughness): <1/10 nm of pattern</p>



One of the origin of LWR

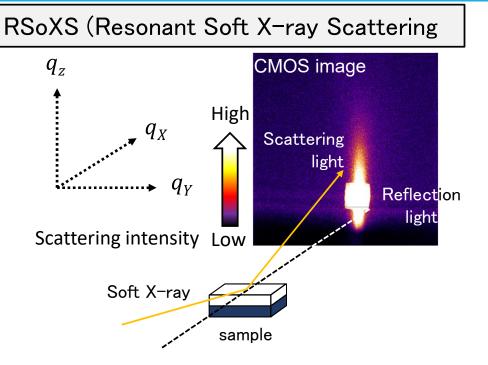
 Chemical composition distribution in the EUV resist film

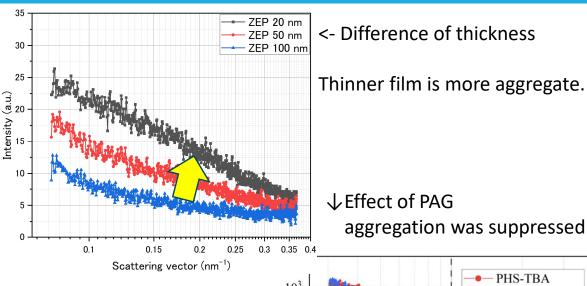


 \rightarrow The photochemical reaction is also not uniform

The chemical composition distribution analysis

Previous study (RSoXS at NewSUBARU BL10)

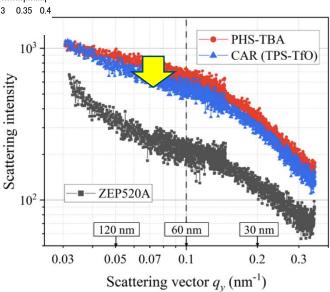




 \downarrow Effect of PAG aggregation was suppressed

Scattering light is translated scattering spectrum.

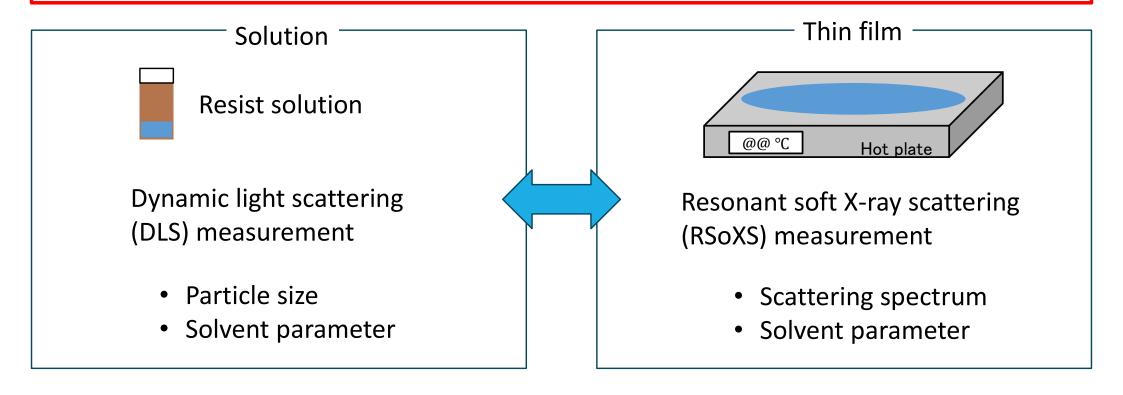
- X axis : <u>Size</u> of scattering source (scattering vector)
- Y axis : <u>Amount</u> of scattering source (intensity) scattering source : aggregation and segregation J. Photopolym. Sci. and Technol. (2022) p.61. & (2023) p.41. **ICPST-41**



This work

The investigation whether the chemical composition distribution in the resist thin film

is affected by the solvent.



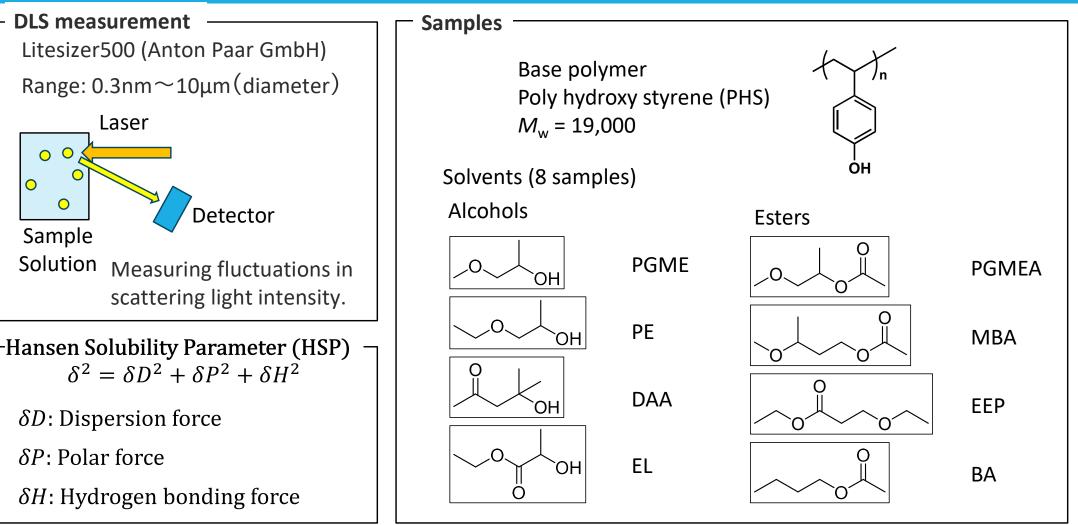
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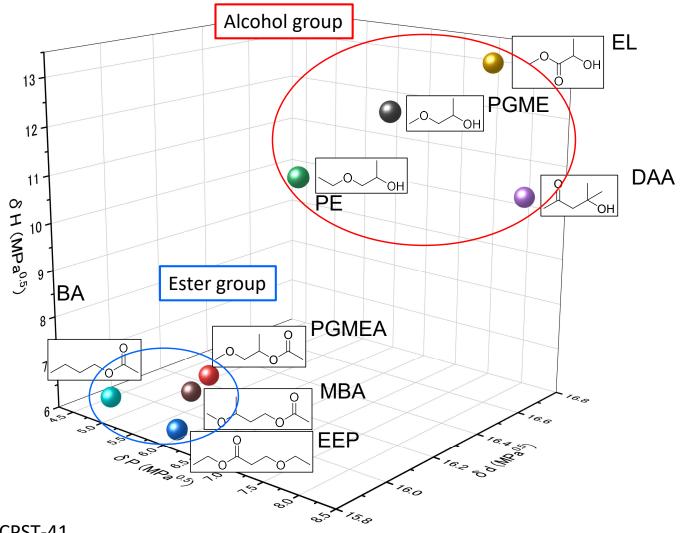
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DLS (Dynamic Light Scattering) measurement setup

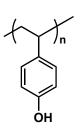


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Difference of solubility



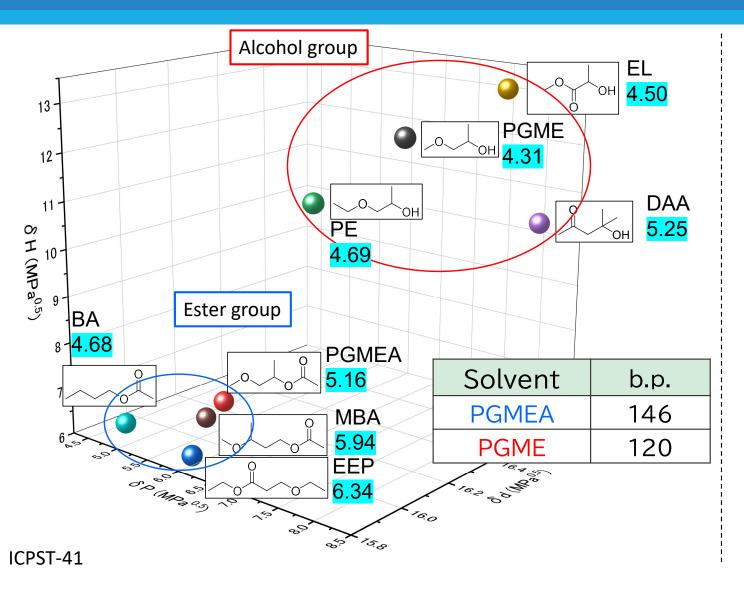
Solvent name Particle size (nm)



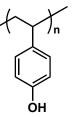
 δH (Hydrogen bond) and δD (dispersion)

Alcohol groups: δH and δD are High
Ester groups: δH and δD are Low
-> Alcohol groups has hydroxyl group.

HSP vs. Particle size



Solvent name Particle size <mark>(nm)</mark>



 δH (Hydrogen bond) and δD (dispersion)

Alcohol groups: δH and δD are High
Ester groups: δH and δD are Low
-> Alcohol groups has hydroxyl group.

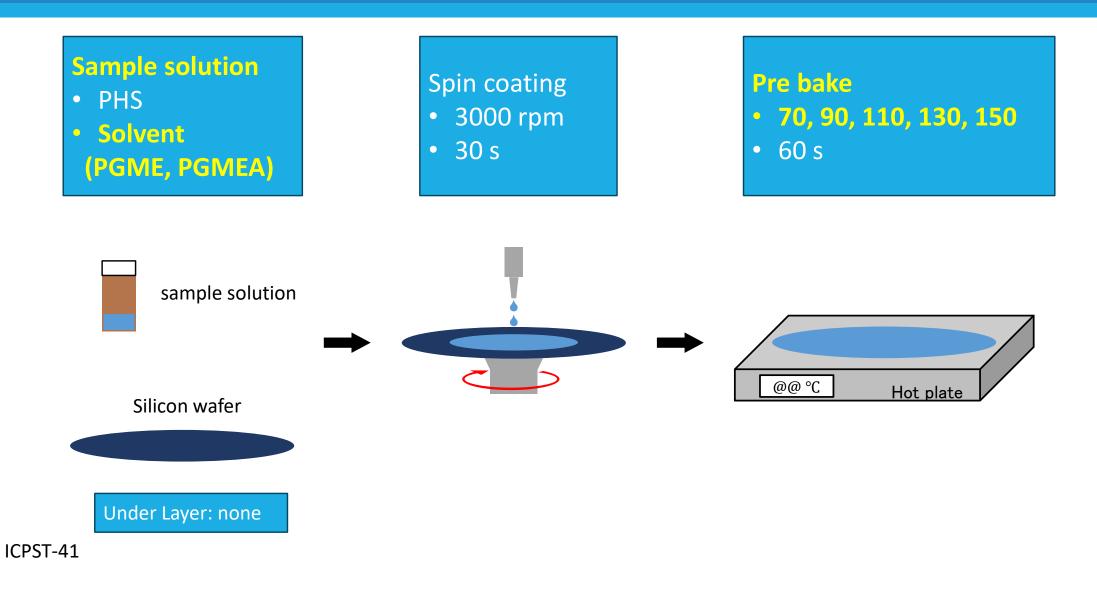
Particle size in

- alcohol solvent: 4~5 nm
- Ester solvent: 4~6 nm

-> slightly bigger (in ester solvent) Ester solvent's affinity is stronger to PHS

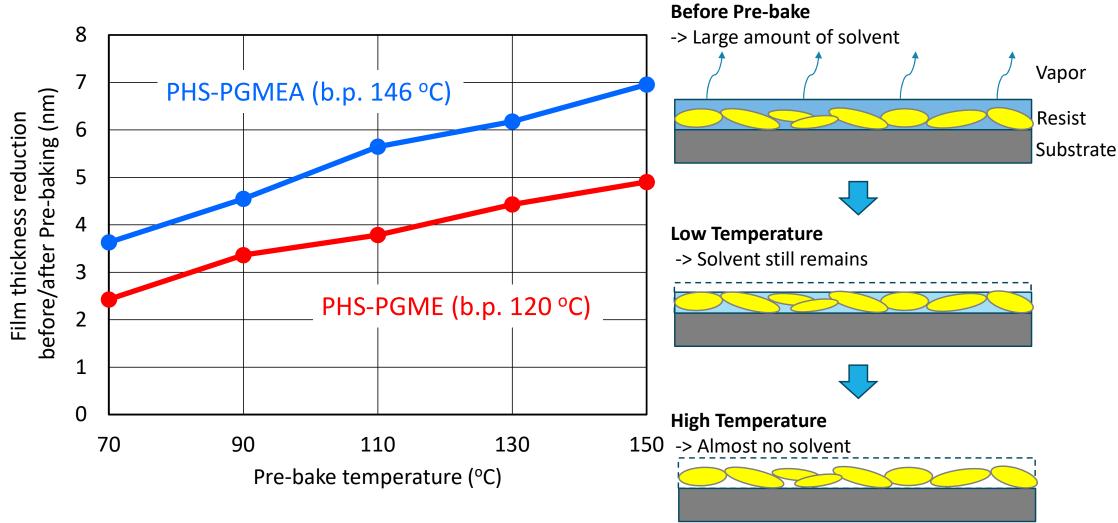
Particle size is correlated to HSP value

Resist coating process



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The relationship between remaining solvent and pre-baking temperature 10

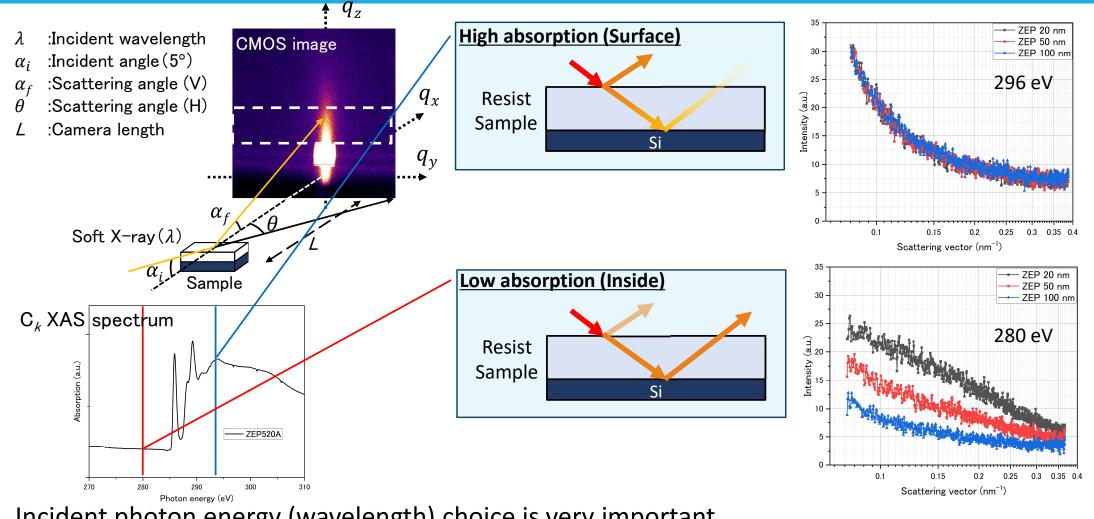


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 DLS measurement
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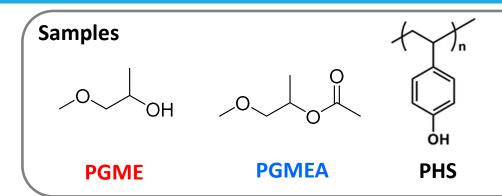
<u>Reflection-mode</u> RSoXS at NewSUBARU BL10



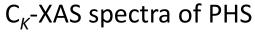
Incident photon energy (wavelength) choice is very important ICPST-41

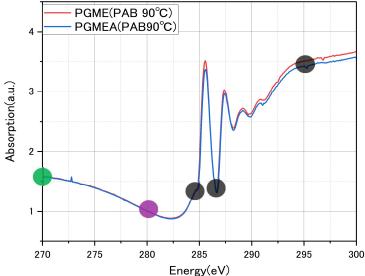
J. Photopolym. Sci. and Technol. (2022) p61.

XAS results



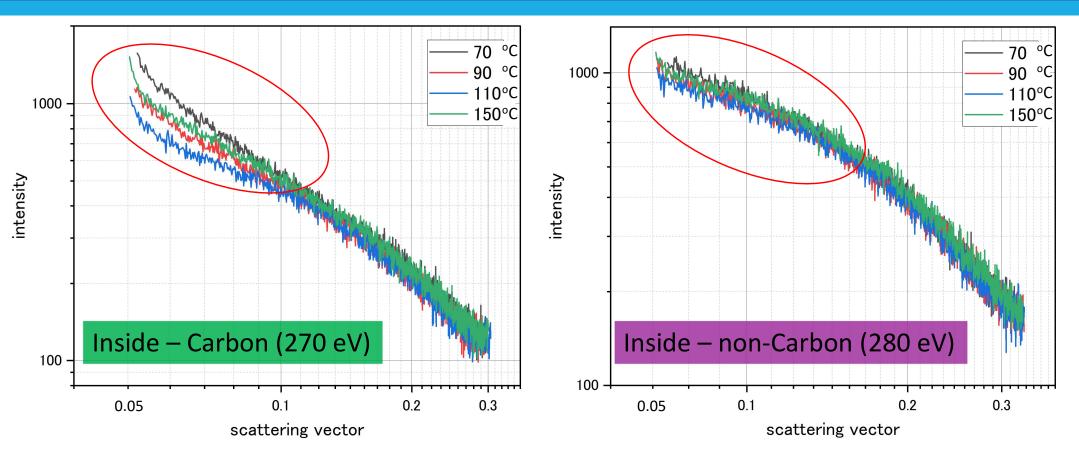
- <u>Pre bake: 70, 90, 110, 130, 150 °C, 60 s</u>
- Thickness: approximately 48 nm





| Information |
|-------------------------|
| Inside – Carbon |
| Inside – Non- Carbon |
| Inside – Phenyl |
| Inside – Acrylate |
| Surface – Carbon |
| |

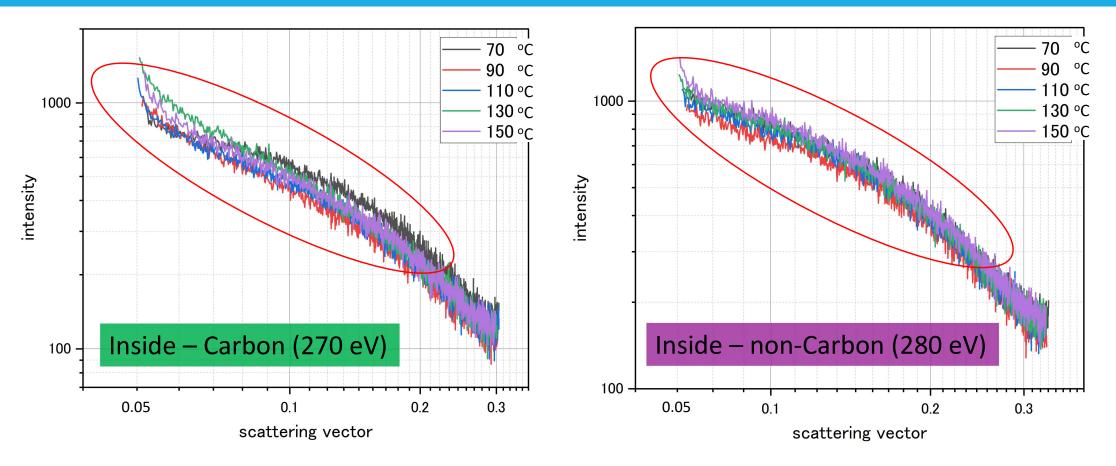
RSoXS result -1. PGME sample



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 $0.05 - 0.1 \text{ nm}^{-1}$ (120 - 60 nm spatial frequency) (\neq Polymer particle size: 4 \sim 5 nm) The intensity of scattering spectra affected by pre-bake temperature.

RSoXS result -2. PGMEA sample

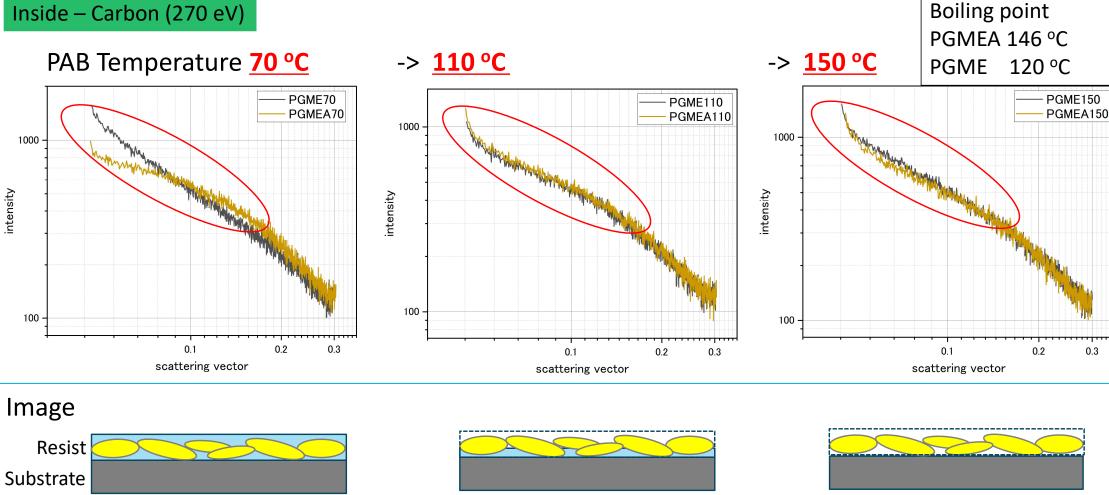


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0.05 – 0.2 nm⁻¹ (120 - <mark>30</mark> nm spatial frequency) (≠ Polymer particle size: 4**~6** nm) → Strong affinity of ester solvent?

RSoXS result -3. Aggregation source

Inside – Carbon (270 eV)



-> Solvent and pre-baking temperature is affected to aggregation in the resist thin film. **ICPST-41**

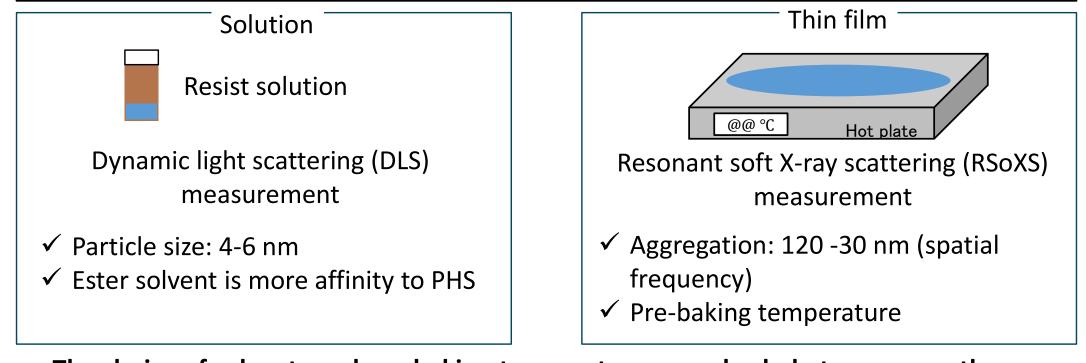
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Summary

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The investigation whether the chemical composition distribution in the resist thin film

is affected by the solvent. (purpose)



The choice of solvents and pre-baking-temperature may also help to suppress the chemical aggregation. Thank you for kind attention!